

N700A-s

Non-Silicone Thermal Conductive Pad

Non-Silicone Thermal Compound N700A-s is made of non-silicon resin material. No low molecular siloxane volatilization and low total volatile gas, no electrical contact & pollution problems. N700A-s is flexible and has great thermal conduction, Low compressive stress and high compressive characteristics can effectively reduce the stress load of components, so that the equipment only needs to bear less mechanical stress, and at the same time, it can have low thermal resistance and high thermal conductivity.

FEATURES

- / Thermal conductivity: 2.5 W/m*K
- / It's made by non-silicone resin materials
- / Low contact thermal resistance
- / With electrical insulation
- / Outstanding thermal conductivity
- / Applicable to optical and sensitive electric components

TYPICAL APPLICATION

- / HDDS
- / Optical appliance
- / 5G base station & infrastructure
- / EV electric vehicle

SPECIFICATIONS

- / Sheet form
- / Die-cut parts



TYPICAL PROPERTIES

PROPERTY	N700A-s	TEST METHOD	UNIT
Color	Gray	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	Customized	ASTM D374	mm
Density	2.4	ASTM D792	g/cm ³
Hardness	60	ASTM D2240	Shore OO
Tensile Strength	1.0	ASTM D412	Kgf/cm ²
Application temperature	-60~125	-	°C
Low molecular Siloxane (D3 to D20 total)	N.D	Gas Chromatography	%
Outgassing CVCN (wt%)	0.0079	By LiPOLY	-
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	10	ASTM D5470 modify	%
Deflection @20 psi	22	ASTM D5470 modify	%
Deflection @30 psi	35	ASTM D5470 modify	%
ELECTRICAL			
Dielectric breakdown	16	ASTM D149	KV/mm
Surface resistivity	>10 ¹¹	ASTM D257	Ohm
Volume resistivity	>10 ¹⁰	ASTM D257	Ohm-m
THERMAL			
Thermal Conductivity	2.5	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.841	ASTM D5470	°C-in ² / W
Thermal impedance@20 psi	0.682	ASTM D5470	°C-in ² / W
Thermal impedance@30 psi	0.494	ASTM D5470	°C-in ² / W
Thermal impedance@40 psi	0.315	ASTM D5470	°C-in ² / W
Thermal impedance@50 psi	0.217	ASTM D5470	°C-in ² / W

The chemical formula indicates that if Cyclic polydimethylsilox-ane (HO-[Si(CH₃)₂O]_n-H) is non-reaction, it's volatile anytime and everywhere. For example, when the electric products which has been put in a confined space, the volatile of low-molecular-weight silox-anes will makes the elecetic products uncontacted.

Thermal Resistance vs. Pressure vs. Deflection

